

Resonac Holdings Corporation

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Resonac Participates in a US-based Leading-edge Semiconductor Consortium as The First Japanese Strategic Material Manufacturing Partner ~ Conduct R&D alongside major U.S. semiconductor companies ~

Resonac Corporation (President: Hidehito Takahashi) will take part in a consortium of semiconductor-related manufacturers named “Texas Institute for Electronics” (hereinafter “TIE”), which is located in the state of Texas, USA. Resonac will be the first Japanese member of TIE as a semiconductor material manufacturer.



TIE is a non-profit organization led by The University of Texas at Austin, and consists of the public and private sectors including the state of Texas, semiconductor manufacturers, defense electronics manufacturers, national laboratories, and academic bodies. Its aim is to advance the roadmap of cutting-edge semiconductor systems by five years (or more than two generations), and to develop them in the United States.. TIE’s strategic member companies include leading semiconductor manufacturers such as AMD, Inc., Micron Technology, Inc., Intel Corporation, Applied Materials, Inc., etc. *

Resonac was invited to participate as the strategic member from the materials manufacturers, as we were recognized by TIE for our comprehensive lineup of materials for the front-end and back-end processes used in advanced semiconductors, our R&D organization specializing in semiconductor packaging "Packaging Solution Center," and our track record in operating the consortium "JOINT2" composed of semiconductor-related companies. TIE plans to launch a prototype line for wafer-scale 2xD and 3D advanced packaging starting from the second half of 2024.

Semiconductors support the lives of the people as social infrastructure. Development of leading-edge semiconductors to be used for AI and next-generation telecommunication requires cooperation between manufacturers of devices, materials, and equipment. Resonac will aim to cooperate with other companies through its participation in TIE, research and development of leading-edge technologies and contributions to solutions of problems concerning semiconductors.

Aiming to accomplish its purpose, “Change society through the power of chemistry,” Resonac will strive to promote co-creation, and contribute to improvement in semiconductors’ performance, which is needed by society.

URL of the website of Texas Institute for Electronics: <https://www.txie.org/>

* As of end of October 2023

[About the Resonac Group]

The Resonac Group is a new company established as a result of the integration of the Showa Denko Group and the Showa Denko Materials Group (former Hitachi Chemical Group) in January 2023. The Group’s annual sales of semiconductor and electronic materials amount to about 400 billion yen, accounting for about 30% of the Group’s annual net sales. The Group especially has global top share of semiconductor materials for packaging process. The integration of the two companies has enabled the Resonac Group to design functions of materials as well as to develop them in-house, going all the way back to raw materials. The new trade name “RESONAC” was created as a combination of two English words, namely, the word of “RESONATE” and “C” as the first letter of CHEMISTRY. The Resonac Group will make the most of its co-creative platform, and accelerate technological innovation with semiconductor manufacturers, material manufacturers, and equipment manufacturers inside and outside Japan.

For detail, please refer to our Website.

Resonac Holdings Corporation: <https://www.resonac.com/>

For further information, contact:

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